



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20240429001.1

**Qualification of RFAB using qualified Process Technology, Die Revision and additional Assembly BOM options for select devices
Change Notification / Sample Request**

Date: April 30, 2024

To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments (TI). The details of this change are on the following pages, and are in alignment with our standard product change notification (PCN) [process](#).

TI requires acknowledgement of receipt of this notification within 30 days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 30 days of this notification, given that samples are not built ahead of the change.

The Proposed First Ship date in this PCN letter is the earliest possible date that customers could receive the changed material. It is our commitment that the changed device will not ship before that date. If samples are requested within the 30 day sample request window, customers will still have 30-days to complete their evaluation regardless of the proposed 1st ship date.

This particular PCN is related to TI's multiyear transition plan for our two remaining factories with 150-millimeter production (DFAB in Dallas, Texas, and SFAB in Sherman, Texas). DFAB will remain open, but will focus on 200-mm production, with a smaller set of technologies. SFAB will close no earlier than 2024 and no later than 2025. As referenced in the "reason for change" below, these changes are part of our multiyear plan to transition these products to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the Change Management team. For sample requests or sample related questions, contact your local Field Sales Representative. As always, we thank you for your continued business.

Change Management Team
SC Business Services

20240429001.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TLV3404IPWR	NULL
TLV3704IPWR	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20240429001.1	PCN Date:	April 30, 2024																		
Title:	Qualification of RFAB using qualified Process Technology, Die Revision and additional Assembly BOM options for select devices																				
Customer Contact:	Change Management Team	Dept:	Quality Services																		
Proposed 1st Ship Date:	July 29, 2024	Sample requests accepted until:	May 30, 2024*																		
*Sample requests received after May 30, 2024 will not be supported.																					
Change Type:																					
☐	Assembly Site	☒	Design																		
☐	Assembly Process	☐	Data Sheet																		
☒	Assembly Materials	☐	Part number change																		
☐	Mechanical Specification	☐	Test Site																		
☐	Packing/Shipping/Labeling	☐	Test Process																		
☐		☐	Wafer Bump Material																		
☐		☐	Wafer Bump Process																		
☒		☒	Wafer Fab Site																		
☐		☒	Wafer Fab Material																		
☐		☒	Wafer Fab Process																		
PCN Details																					
Description of Change:																					
Texas Instruments is pleased to announce the qualification of its RFAB fabrication facility as an additional Wafer Fab option in addition to an Assembly BOM options for the devices listed below.																					
<table border="1"> <thead> <tr> <th colspan="3">Current Fab Site</th> <th colspan="3">Additional Fab Site</th> </tr> <tr> <th>Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> <th>Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> </tr> </thead> <tbody> <tr> <td>DL-LIN</td> <td>LBC3S</td> <td>150 mm</td> <td>RFAB</td> <td>LBC9</td> <td>300 mm</td> </tr> </tbody> </table>				Current Fab Site			Additional Fab Site			Fab Site	Process	Wafer Diameter	Fab Site	Process	Wafer Diameter	DL-LIN	LBC3S	150 mm	RFAB	LBC9	300 mm
Current Fab Site			Additional Fab Site																		
Fab Site	Process	Wafer Diameter	Fab Site	Process	Wafer Diameter																
DL-LIN	LBC3S	150 mm	RFAB	LBC9	300 mm																
The die was also changed as a result of the process change.																					
Construction differences are as follows:																					
<table border="1"> <thead> <tr> <th></th> <th>Current</th> <th>Proposed</th> </tr> </thead> <tbody> <tr> <td>Wire diam/type</td> <td>0.96mil Cu</td> <td>0.80mil Cu</td> </tr> </tbody> </table>					Current	Proposed	Wire diam/type	0.96mil Cu	0.80mil Cu												
	Current	Proposed																			
Wire diam/type	0.96mil Cu	0.80mil Cu																			
Qual details are provided in the Qual Data Section.																					
Reason for Change:																					
These changes are part of our multiyear plan to transition products from our 150-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.																					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																					
None																					
Impact on Environmental Ratings:																					
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.																					
RoHS	REACH	Green Status	IEC 62474																		
☒ No Change	☒ No Change	☒ No Change	☒ No Change																		

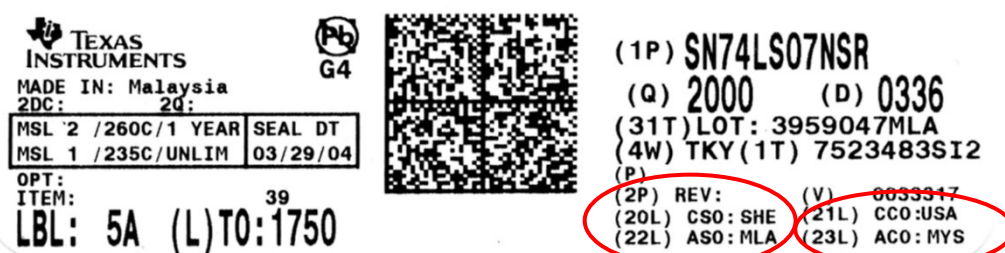
Changes to product identification resulting from this PCN:**Fab Site Information:**

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DL-LIN	DLN	USA	Dallas
RFAB	RFB	USA	Richardson

Die Rev:**Current****New**

Die Rev [2P]	Die Rev [2P]
A	A

Sample product shipping label (not actual product label):

**Product Affected:**

TLV3404CPWR	TLV3404IPWR	TLV3704IPWR
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For alternate parts with similar or improved performance, please visit the product page on [TI.com](http://ti.com)

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TLV3704IPWR	QBS Reference: ADS1259BIPWR	QBS Reference: OPA4991QPWRQ1
HAST	A2	Biased HAST	110C/85%RH	264 Hours	-	-	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0
HTOL	B1	Life Test	150C	300 Hours	-	-	3/231/0
ESD	E2	ESD CDM	-	500 Volts	1/3/0	-	-
ESD	E2	ESD HBM	-	2000 Volts	1/3/0	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-

- QBS: Qual By Similarity
- Qual Device TLV3704IPWR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2310-039

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TLV3404IPWR	QBS Reference: ADS1259BIPWR	QBS Reference: OPA4991QPWRQ1
HAST	A2	Biased HAST	110C/85%RH	264 Hours	-	-	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0
HTOL	B1	Life Test	150C	300 Hours	-	-	3/231/0
ESD	E2	ESD CDM	-	1500 Volts	1/3/0	-	-
ESD	E2	ESD HBM	-	2000 Volts	1/3/0	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-

- QBS: Qual By Similarity
 - Qual Device TLV3404IPWR is qualified at MSL1 260C
 - Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
 - The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
 - The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
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- Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2404-039

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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